

FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

**Title of
Invention**

[FLIP-CHIP SUBSTRATE AND FLIP-CHIP BONDING PROCESS THEREOF]

Application Number :

Date :

First Named Applicant: Mr. Yu-Wen Chen

Attorney Docket Number: 10039-US-PA

TOTAL FEE AUTHORIZED \$ 826

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as large entity

BASIC FILING FEE

Fee Description	Fee Code	Amount \$	Fee Paid \$
Utility Filing Fee	1001	750	750
Subtotal For Basic Filing Fees: \$ 750			

EXTRA CLAIM FEES

Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$
Total Claims : 22	2	1202	18	36
Independent Claims : 3	0	1201	84	0
Subtotal For Extra Claims Fees: \$ 36				

ASSIGNMENT FEES

Fee Description	Property Number	Quantity	Fee Code	Amount \$	Fee Paid \$
Recording Each Patent Assignment Per Property Fee	00000000	1	8021	40	40
Subtotal For Additional Fees: \$40					

AUTHORIZED BILLING INFORMATION**The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:**

Credit account number: 1009
Expiration Date (YYYYMMDD): 2005-10-31
Authorized name: LEE, HUAI-LU
Billing address: 99999